



DISCO DFG 8540 Fully automatic in-feed surface grinder (Item JL1035)

Max wafer diameter: 200mm Configured with ultra-thin wafer handling

Configured for DBG options

Configured with Orientation Flat/Notch Alignment

Configured with Interior Grind Water Nozzle

Configured with Chuck Table/Spinner Table Positioning and Stopping System

Configuration: 2-spindles, 3-rotary-chuck table

Grinding Method: In-feed grinding with wafer rotation

Spindle Type: Air bearing with high frequency motor

Number of axes: 2

Output: 4.2 (kW)

Revolution speed (min-1)[rpm]: 1,000 - 7,000

Z-axis vertical stroke(mm): 120 (with zero point)

Z-axis vertical grinding feed speed (mm/s): 0.0001 - 0.08

Z-axis vertical fast feed speed (mm/s): 50 Min.

Z-axis vertical movement (um): 0.1 Min.

Z-axis vertical movement resolution (um): 0.1 Height Gauge

Measurement range (um): 0 - 1,800 Resolution (um): 0.1

Repeatability (um): ± 0.5

Wafer Chuck Table type: Porous chuck table

Chuck method: Vacuum

Number of revolutions: 0 300

Number of chuck tables: 3

Chuck table cleaning: Backflushing of water and compressed air is combined with oilstone cleaning and brush cleaning

Spark Out (chuck table revolutions setting): 0 999

Grinding Wheel Diamond wheel (mm): ϕ 200

Wafer Handling Section / Wafer Cleaning Section Cassette storage quantity: 2

Spinner unit: Water washing and drying

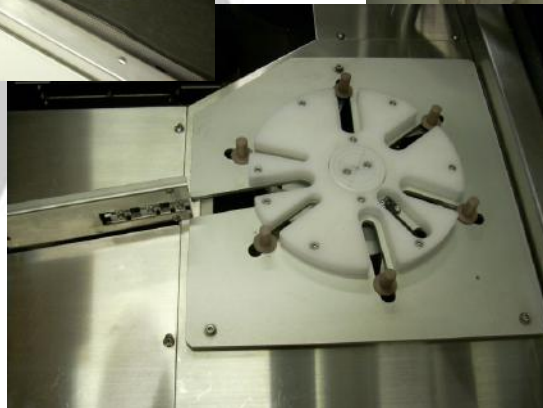
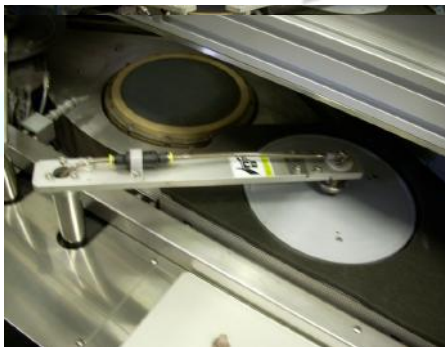
Vacuum Unit: Discharge speed 29/36 (m³/h) 50/60 (Hz)

Achievable pressure (kPa/G): -90 (water supply temperature 15°C, water supply flow rate 1L/min)

Grinding Accuracy: Thickness variation within one wafer (um) less than 1.5 (when grinding 8" wafers with included chuck tables)

Thickness variation between wafers (um) less than ± 3

Power: 200/200-220V, 50/60 Hz, 5.9A, 3 Ph



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